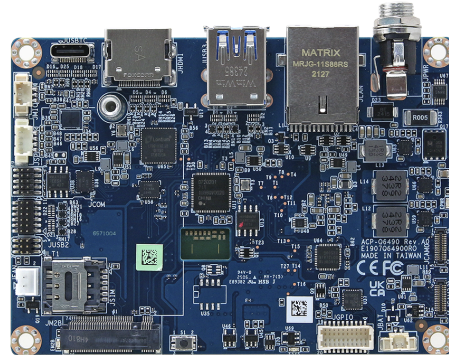


ACP-Q6490

PRELIMINARY



Product Features

- Qualcomm QCS6490 high level platform up to 2.7GHz
- Thin client concept and ruggedize, support a wide temperature range
- Strong Connectivity for 5G, WiFi6, Ethernet, and BT
- AI Engine up to 12TOPS
- Various video interfaces and I/O connections: 2 USB3.1, HDMI, 2 COM, 16bit DIO, 2 MIPI-CSI
- Ideal for embedded applications in fields like automotive markets, retail and box pc with AI solution

Specification

System Information

Processor QCS6490
Qualcomm® Kryo™ 670, 8 cores, up to 2.7 GHz, 12 TOPS (INT8)

System Memory LPDDR4, 8GB (optional 4GB to 16GB)

Software Support

OS Andriod (first), Ubuntu (by demand), Windows(by demand)

Expansion

Expansion 1 x M.2 B key 3052 (USB3.1) reference RM520N-GL Quectel
1 x Nano SIM slot (push and pull)

Storage

UFS Support UFS 3.1, default 128GB

Power Requirement

DC Input DC 12V

I/O

UART	1 x Debug (UART (TX,RX))
GPIO	1 x 16-bit DIO
RS232	1 x RS-232 (RX, TX, RTS, CTS)
RS485	1 x RS485
USB	3 x USB 2.0 (by pin header) 2 x USB 3.0 type A 1 x USB 3.1 type C (download only)
Display	HDMI or DP
Audio	1 x Line out/(stereo), 1x Mic in (mono), audio jack
Network	1 x GbE (RJ-45)
WIFI	802.11ax Wifi
Camera	2 x MIPI-CSI2 for 4-lanes camera, reference to IMX577 and GC5035
SD	1 x uSD3.0 card
RTC	Supported

System Control

LED Indicator	1 x System LED 1 x Power LED
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Mechanical & Environmental

Operating Temp.	-20°C ~ 70°C
Storage Temp.	-40°C ~ 85°C
Dimension (L x W)	2.5" 100mm (3.94") x 72mm (2.83")